



DOCUMENT CHANGE REQUEST

DCR number 402

Changes required for: N/A

Originator: Daniel VALLEE

Date: 2008/04/10

Date sent: 2008/04/10

Organisation: CNES

Status: IMPLEMENTED

Title: Requirements for Lead Materials and Finishes for Components for Space Application

Number: 23500

Issue: 3

Other documents affected:

Page:

Paragraph 3.3: Type 4 description

Paragraph 6: Type S

Paragraph:

Paragraph 3.3: Type 4 description

Paragraph 6: Type S

Original wording:

Proposed wording:


Para 3.3: Type 4: Hot solder dip may be used over final finish Type 2, 7, 8, 12 or 14 gold plating, but prior to this, the leads or terminals shall be de-golded using the procedure defined in para. 4.3(a) of this document.

Para 6: Add S in the table for Type S4

Justification:

Para 3.3: Hot solder dip can be performed on type 14

Para 6: Type S4 lead can be soldering

Attachments:
N/A
Modifications:
N/A
Approval signature:

Date signed:
2008-04-10